

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## METHOD OF FABRICATING INTER-LAYER SOLID CONDUCTIVE RODS

the	specification of whic	:h				
<u>_x</u>	is attached hereto.					
	was filed on					
	as Application Seri	ial No	and was amended on		·	
ap ap ap	ecification, including to a cknowledge the plication in accordance I hereby claim fore plication(s) for patent	the claims, as amender e duty to disclose info ce with Title 37, Code o eign priority benefits un or inventor's certificate inventor's certificate ha	and understand the content of by any amendment referred ormation which is material to of Federal Regulations, § 1.5 ader Title 35, Untied States Co e listed below and have also it aving a filing date before that	d to above. the patent 66(a). Code, § 119 dentified bel	tability of this of any foreign ow any foreign	
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
					x	
I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:						
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## COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

	Signature: Jao-Ehin Cheng Date: June, 15, 2001				
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**Issue Dt:** 

## **Patent Assignment Abstract of Title**

**Total Assignments: 2** 

Applicati n #: 09927723 Filing Dt: 08/10/2001 Patent #: NONE

CT #: NONE Publicati n #: 20030029729 Pub Dt: 02/13/2003

Inventors: Jao-Chin Cheng, Chang-Chin Hsieh, Chih-Peng Fan, Chih-Hao Yeh

Title: Method of fabricating inter-layer solid conductive rods

Assignment: 1

Reel/Frame: 012079/0392 Received: Recorded: Mailed: Pages: 08/21/2001 08/10/2001 10/22/2001 3

Conveyance: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

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FAN, CHIH-PENG Exec Dt: 06/15/2001

YEH, CHIH-HAO **Exec Dt**: 06/15/2001

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Assignment: 2

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Conveyance: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

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Search Results as of: 8/21/2003 8:38:40 A.M.

If you have any comments or questions concerning the data displayed, contact OPR / Assignments at 703-308-9723 Web interface last modified: Oct. 5, 2002

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